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17.5

(1)

1.0

OUTLINE DRAWING

4MIN

GF-21

MGF0911A

Unit:millimeters

L, S BAND POWER GaAs FET

DESCRIPTION

The MGF0911A, GaAs FET with an N-channel schottky gate, is designed for use in UHF band amplifiers.

FEATURES

 Class A operation 	
 High output power 	
P1dB=41dBm(TYP)	@2.3GHz
 High power gain 	
GLP=11dB(TYP)	@2.3GHz
High power added efficiency	
add=40%(TYP)	@2.3GHz,P1dB

• Hermetically sealed metal-ceramic package with ceramic lid

APPLICATION

UHF band power amplifiers

QUALITY GRADE

• IG

RECOMMENDED BIAS CONDITIONS

- VDS=10V
- ID=2.6A
- Rq=50
- Refer to Bias Procedure

6.35 2-R1.25 4MIN 2 (2 3 14.3 9.4 10.0

(1) GATE

(3) DRAIN

(2) SOURCE(FLANGE)

ABSOLUTE MAXIMUM RATINGS (Ta=25°C)

Symbol	Parameter		Ratings	Unit			
Vgdo	Gate to drain voltage		-15	V			
Vgso	Gate to source voltage		-15	V			
ld	Drain current		10	A			
lgr	Reverse gate current		30	mA			
lgf	Forward gate current		63	mA			
Рт	Total power dissipation	*1	37.5	W			
Tch	Channel temperature		175	°C			
Tstg	Storage temperature		-65 to +175	°C			

*1:TC=25°C

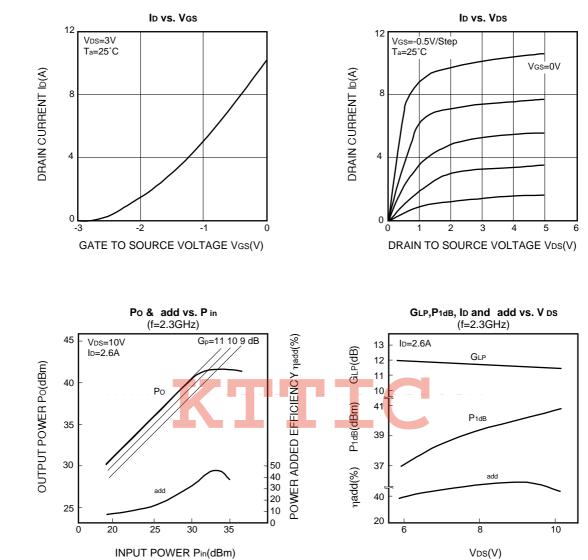
ELECTRICAL CHARACTERISTICS (Ta=25°C)

Parameter		Limits			11.2
i alameter		Min	Тур	Max	Unit
Saturated drain current	VDS=3V,VGS=0V	-	-	10	A
Transconductance	VDS=3V,ID=2.6A	-	3.0	-	S
Gate to source cut-off voltage	VDS=3V,ID=20mA Test conditions	-2	-	-5	V
Output power at 1dB gain compression		40	41	-	dBm
Linear power gain *2	VDS=10V,ID=2.0A,I=2.3GHZ	10	11	-	dB
Power added efficiency at P1dB		-	40	-	%
Thermal resistance *1	V f method	-	_	4.0	°C/W
T G C C C T	ransconductance Gate to source cut-off voltage Output power at 1dB gain ompression inear power gain *2 Power added efficiency at P1dB	ransconductance VDS=3V,ID=2.6A Gate to source cut-off voltage VDS=3V,ID=20mA Test conditions Output power at 1dB gain ompression VDS=3V,ID=20mA Test conditions VDS=10V,ID=2.6A,f=2.3GHz VDS=10V,ID=2.6A,f=2.3GHz Yower added efficiency at P1dB Vf method	Saturated drain current VDS=3V,VGS=0V - Transconductance VDS=3V,ID=2.6A - Sate to source cut-off voltage VDS=3V,ID=20mA Test conditions -2 Output power at 1dB gain ompression VDS=10V,ID=2.6A,f=2.3GHz 40 Inear power gain *2 Yower added efficiency at P1dB V f method -	Saturated drain current VDS=3V,VGS=0V - - Gransconductance VDS=3V,ID=2.6A - 3.0 Grate to source cut-off voltage VDS=3V,ID=20mA Test conditions -2 - Dutput power at 1dB gain ompression VDS=3V,ID=20mA Test conditions -2 - VDS=10V,ID=2.6A,f=2.3GHz 40 41 10 11 - 40 hermal resistance *1 V f method	Saturated drain currentVDS=3V,VGS=0V10TransconductanceVDS=3V,ID=2.6A-3.0-Sate to source cut-off voltageVDS=3V,ID=20mA Test conditions-25Dutput power at 1dB gain ompressionVDS=10V,ID=2.6A,f=2.3GHz4041-Nower added efficiency at P1dBVf method40-

1:Channel to case *2:Pin=25dBm

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TYPICAL CHARACTERISTICS

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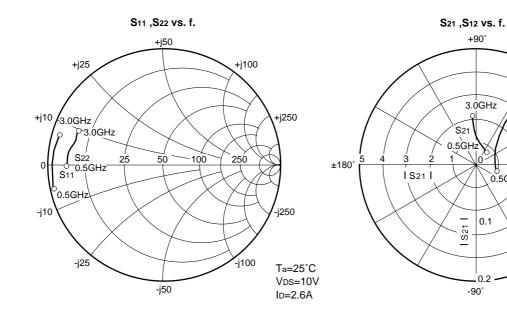
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3.0GHz

0°

S12

0.5GHz



S PARAMETERS (Ta=25°C,VDs=10V,ID=2.6A)

Freq. (GHz)	S11		S 21		S 12		S22		к	MSG/MAG
	Magn.	Angle(deg.)	Magn.	Angle(deg.)	Magn.	Angle(deg.)	Magn.	Angle(deg.)	IX.	(dB)
0.50	0.986	-167.3	2.046	91.2	0.008	44.1	0.913	-178.6	0.515	23.1
0.60	0.985	-171.3	1.833	87.9	0.010	44.2	0.911	-179.9	0.567	22.7
0.70	0.984	-174.3	1.515	86.1	0.011	44.6	0.909	178.6	0.583	21.8
0.80	0.983	-175.5	1.356	83.6	0.012	44.9	0.907	178.2	0.675	21.2
0.90	0.982	-172.1	1.233	84.0	0.013	45.3	0.904	177.7	0.683	20.3
1.00	0.981	-173.9	1.128	81.1	0.013	45.8	0.902	176.6	0.713	19.6
1.10	0.980	-175.3	1.033	79.7	0.015	46.4	0.898	175.7	0.736	19.3
1.20	0.979	-176.3	0.970	77.8	0.015	46.8	0.895	176.6	0.785	18.7
1.30	0.978	-176.9	0.919	75.8	0.016	47.0	0.889	176.0	0.815	18.2
1.40	0.976	-177.9	0.878	73.6	0.017	47.3	0.883	175.6	0.835	17.5
1.50	0.975	-178.2	0.845	71.6	0.018	47.6	0.875	175.2	0.900	17.1
1.60	0.974	-179.3	0.811	69.4	0.019	48.0	0.865	175.0	0.951	16.8
1.70	0.973	-179.8	0.788	67.8	0.020	48.4	0.858	174.6	0.989	15.8
1.80	0.972	179.5	0.771	65.8	0.020	48.9	0.850	173.6	1.011	14.7
1.90	0.971	178.6	0.754	64.1	0.022	49.2	0.843	173.4	1.050	14.1
2.00	0.970	176.7	0.653	63.1	0.023	49.6	0.837	172.6	1.149	13.9
2.10	0.969	175.9	0.638	60.9	0.023	49.9	0.833	174.1	1.170	13.7
2.20	0.968	175.1	0.638	59.0	0.023	50.4	0.829	173.6	1.221	12.7
2.30	0.967	174.1	0.635	56.3	0.024	50.7	0.826	172.9	1.242	12.3
2.40	0.966	173.1	0.625	54.2	0.025	51.0	0.823	171.0	1.256	11.9
2.50	0.965	172.3	0.628	52.3	0.025	51.2	0.820	170.3	1.267	11.6
2.60	0.965	171.2	0.634	51.3	0.027	51.6	0.818	168.8	1.292	11.4
2.70	0.964	170.2	0.635	48.9	0.027	51.9	0.816	167.1	1.315	11.0
2.80	0.963	168.7	0.646	46.3	0.028	52.3	0.814	165.7	1.327	10.1
2.90	0.962	167.6	0.642	44.0	0.029	52.5	0.812	164.6	1.366	9.8
3.00	0.961	166.3	0.651	41.0	0.029	52.7	0.811	162.7	1.412	9.4

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